

# Advanced Semiconductor Engineering, Inc.



## **FOR IMMEDIATE RELEASE**

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## **ADVANCED SEMICONDUCTOR ENGINEERING, INC. PRICES GUARANTEED BOND OFFERING**

Taipei, Taiwan, R.O.C., July 17, 2014— Advanced Semiconductor Engineering, Inc. (TAIEX: 2311, NYSE: ASX) ("ASE", or the "Company") today announced that it has priced an offering of US\$300 million aggregate principal amount of guaranteed bonds due 2017 offered by Anstock II Limited, its wholly owned subsidiary (the "Bonds"). The Bonds are unconditionally and irrevocably guaranteed by ASE. The proceeds will be used to fund certain eligible projects to promote the Company's transition to low-carbon and climate resilient growth. Examples of eligible projects may include, among other projects, green buildings, waste water recycling projects, waste water management and projects promoting energy efficiency in manufacturing processes. The Bonds were offered outside the United States pursuant to Regulation S under the Securities Act of 1933, as amended (the "Act").

The Bonds have not been and will not be registered under the Act and these securities may not be offered or sold in the United States absent registration or an applicable exemption from registration requirements.

This press release does not constitute an offer to sell or the solicitation of an offer to buy any security and shall not constitute an offer, solicitation or sale in any jurisdiction in which such offering would be unlawful.

### **About ASE Group**

*The ASE Group is the world's largest provider of independent semiconductor manufacturing services in assembly and test. The Group develops and offers a wide portfolio of technology and solutions including IC test program design, front-end engineering test, wafer probe, wafer bump, substrate design and supply, wafer level package, flip chip, system-in-package, final test and electronic manufacturing services through Universal Scientific Industrial Co. Ltd., a member of the ASE Group. For more information about the ASE Group, please visit [www.aseglobal.com](http://www.aseglobal.com).*

### **Safe Harbor Notice**

This press release contains "forward-looking statements" within the meaning of Section 27A of the United States Securities Act of 1933, as amended, and Section 21E of the United States Securities Exchange Act of 1934, as amended, including statements regarding our future results of operations and business prospects. Although these forward-looking statements, which may include statements regarding our future results of operations, financial condition or business prospects, are based on our own information and information from other sources we believe to be reliable, you should not place undue reliance on these

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forward-looking statements, which apply only as of the date of this press release. The words “anticipate,” “believe,” “estimate,” “expect,” “intend,” “plan” and similar expressions, as they relate to us, are intended to identify these forward-looking statements in this press release. Our actual results of operations, financial condition or business prospects may differ materially from those expressed or implied in these forward-looking statements for a variety of reasons, including risks associated with cyclical and market conditions in the semiconductor or electronic industry; changes in our regulatory environment, including our ability to comply with new or stricter environmental regulations and to resolve environmental liabilities; demand for the outsourced semiconductor packaging, testing and electronic manufacturing services we offer and for such outsourced services generally; the highly competitive semiconductor or manufacturing industry we are involved in; our ability to introduce new technologies in order to remain competitive; international business activities; our business strategy; our future expansion plans and capital expenditures; the strained relationship between the Republic of China and the People’s Republic of China; general economic and political conditions; the recent global economic crisis; possible disruptions in commercial activities caused by natural or human-induced disasters; fluctuations in foreign currency exchange rates; and other factors. For a discussion of these risks and other factors, please see the documents we file from time to time with the Securities and Exchange Commission, including our 2013 Annual Report on Form 20-F filed on April 17, 2014.